

**AMENDMENTS TO THE SPECIFICATION AND ABSTRACT:**

*Please replace the paragraph beginning at page 6, line 26, with the following rewritten paragraph:*

18 The polishing assembly 10 comprises a top ring 40 (not shown) for holding a substrate (workpiece) to be polished such as a semiconductor wafer, a turntable 12 constituting a polishing table and having a polishing surface 12a thereon, and a dresser 11 for dressing the polishing surface. In the present embodiment, the polishing surface 12a is constituted by an upper surface of a polishing pad attached to the turntable 12. The substrate to be polished is placed between the top ring 40 and the polishing surface 12a on the turntable 12. While the substrate is pressed against the polishing surface 12a under a certain pressure by the top ring 40, the turntable 12 and the top ring are respectively rotated to polish the substrate. The polishing surface 12a is dressed by the dresser 11 at a suitable time to recover original polishing performance.